

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A light emitting apparatus comprising: ~~[[an]]~~ a co-fired aluminum nitride ~~co-fired~~ substrate; and a light emitting device arranged on a front surface of the co-fired aluminum nitride substrate,

wherein the front surface of the co-fired aluminum nitride substrate, on which the light emitting device is arranged, is mirror-polished so as to have a surface roughness of 0.3 μm Ra or less, ~~[[and]]~~

wherein the light emitting ~~apparatus further~~ device comprises a vapor-deposited metal film and via holes, the vapor-deposited metal film being arranged on the front surface of the co-fired aluminum nitride substrate around the light emitting device and having a reflectivity of 90% or more with respect to light emitted from the light emitting device, and the via holes penetrating the co-fired aluminum nitride substrate from the front surface, on which the light emitting device is arranged, to the rear surface of the co-fired aluminum nitride substrate to thereby allow conduction to the light emitting device from the rear surface, and
wherein the vapor-deposited metal film comprises aluminum or silver.

Claim 2 (Canceled).

Claim 3 (Currently Amended): The light emitting apparatus according to claim 1, comprising a LED chip as the light emitting device and further comprising at least one peripheral component arranged on the co-fired aluminum nitride substrate, wherein the at least one peripheral component is ~~[[and]]~~ selected from the group consisting of diodes for inhibiting reverse current, resistances, and thermistors.

Claim 4 (Currently Amended): The light emitting apparatus according to claim 1, wherein the co-fired aluminum nitride substrate carrying the light emitting device has a surface roughness of 0.1 μm Ra or less.

Claim 5 (Currently Amended): The light emitting apparatus according to claim 1, wherein the light emitting device is mounted on the co-fired aluminum nitride substrate ~~by a flip-chip-assembly technique~~ through a metal bump.

Claim 6 (Currently Amended): The light emitting apparatus according to claim 1, wherein a white resist film is arranged on an exposed front surface of the co-fired aluminum nitride substrate other than a region where the vapor-deposited metal film is arranged.

Claim 7 (Currently Amended): The light emitting apparatus according to claim 6, wherein the white resist film comprises a solder resist ink and is formed by screen printing method.

Claim 8 (New): The light emitting apparatus according to claim 1, wherein the vapor-deposited metal film has a thickness of 1 to 5 μm .

Claim 9 (New): The light emitting apparatus according to claim 1, wherein the vapor-deposited metal film is deposited via a chemical vapor deposition method or a sputtering method.